AMPMODU

TE Internal #: 8-146280-6

PCB Mount Header, Vertical, Board-to-Board, 36 Position, 2.54 mm [.1 in] Centerline, Breakaway, Gold, Through Hole - Solder, Signal,

Black

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical
Connector System: Board-to-Board

Number of Positions: **36**Number of Rows: **1**

Features

Product Type Features

PCB Connector Assembly Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Breakaway
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

PCB Mount Orientation	Vertical
Number of Positions	36
Number of Rows	1
Board-to-Board Configuration	Parallel

Body Features

Primary Product Color	Black	
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Contact Features

PCB Contact Termination Area Plating Material Thickness	2.54 – 5.08 μm[100 – 200 μin]
Contact Underplating Material Thickness	1.27 µm[50 µin]
PCB Contact Termination Area Plating Material Finish	Matte
Contact Shape & Form	Square
Contact Underplating Material	Nickel



PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Copper Alloy
Contact Mating Area Plating Material	Gold
Contact Mating Area Plating Material Thickness	.38 μm[15 μin]
Contact Type	Pin
Contact Current Rating (Max)	3 A
Termination Features	
Termination Method to Printed Circuit Board	Through Hole - Solder
Mechanical Attachment	
Mating Alignment	Without
PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	2.54 mm[.1 in]
Housing Material	LCP
Dimensions	
PCB Thickness (Recommended)	1.6 mm[.063 in]
Usage Conditions	
Operating Temperature Range	-55 – 125 °C[-67 – 257 °F]
Operation/Application	
Circuit Application	Signal

Packaging Features

UL Flammability Rating

Industry Standards

Packaging Type Carton

UL 94V-0

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold



EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Low Bromine/Chlorine - Br and Cl < 900 ppm per homogenous material. Also BFR /CFR/PVC Free
Solder Process Capability	Pin-in-Paste capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Customers Also Bought





Documents

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_8-146280-6_D.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_8-146280-6_D.3d_igs.zip

English

Customer View Model

ENG_CVM_8-146280-6_D.3d_stp.zip

English

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By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages

AMPMODU Interconnetion System

AMPMODU Interconnetion System

English